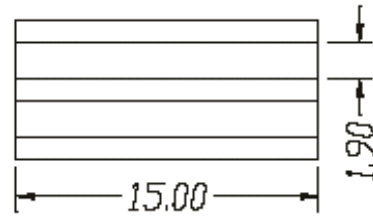
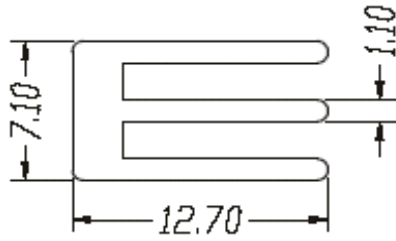


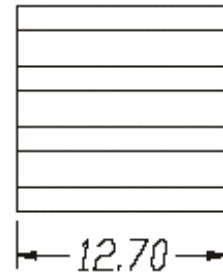
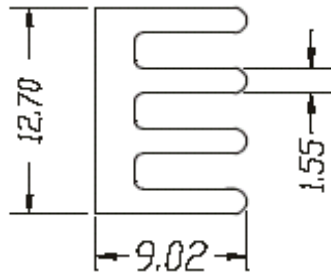
BGA HEATSINK (Bidirectrion)



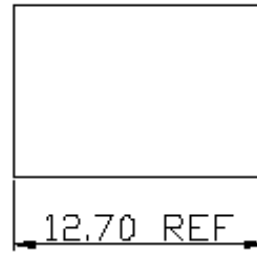
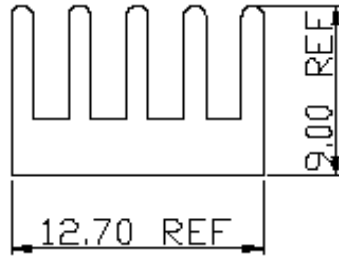
1251A000



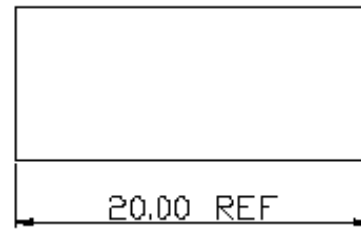
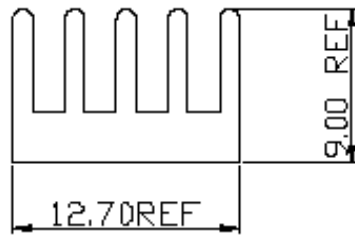
1252A000



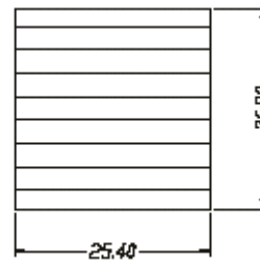
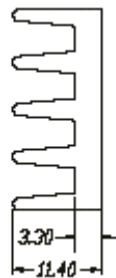
1253A000



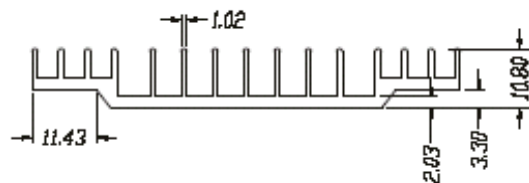
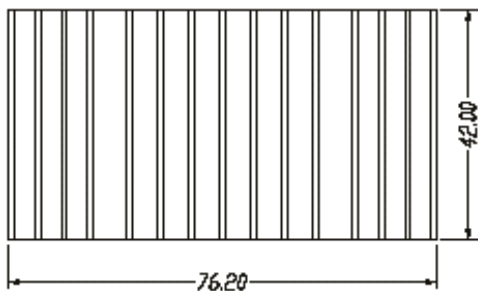
1254A000



1255A000



1256A000



BGA HEATSINK (Omnidirection)

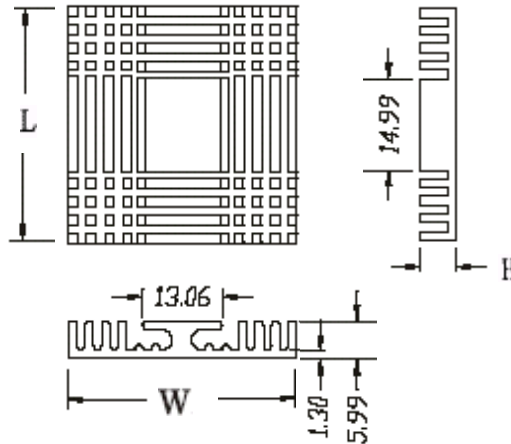
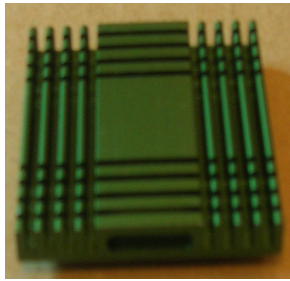


Fig. 1

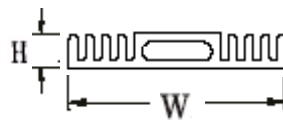
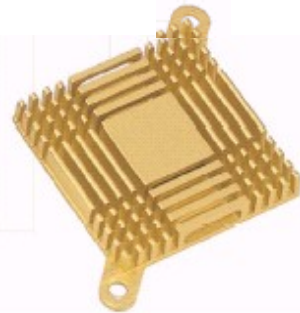


Fig. 2

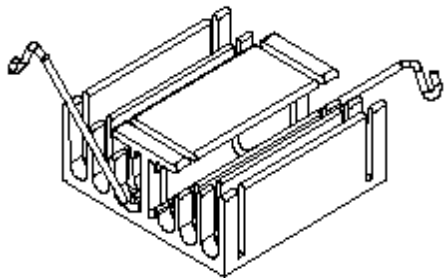


Fig. 4

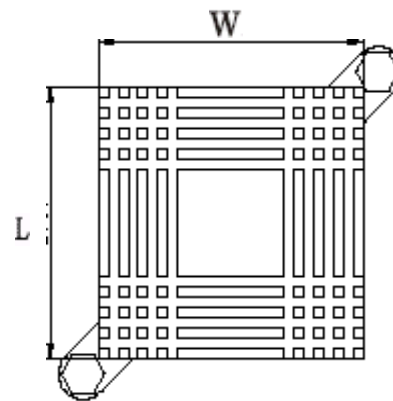


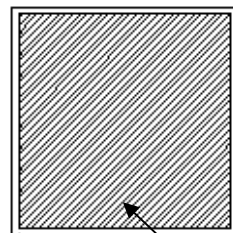
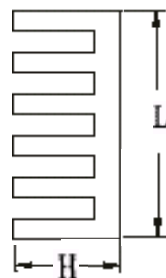
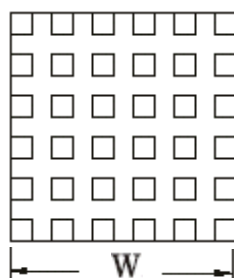
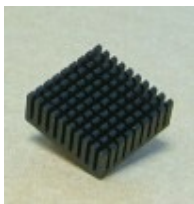
Fig. 3

PART NO	"W"	"L"	"H"	Fig
1127A405/760	37.40	37.40	6.00	2
1155A801	37.40	37.40	6.20	3
1131A888	37.00	37.00	15.00	1, 4
1150A405/888	37.50	37.50	15.40	1
1153A801	28.00	28.00	6.00	3
1156A801	37.40	37.40	10.00	3
1131A888/405	37.00	37.00	15.60	3, 4
1178A888	38.00	42.80	22.30	4
1185A889	42.20	42.20	30.80	4
1249A801	33.38	32.53	6.00	3
1250A801	37.50	37.50	6.00	3

Note:

Heatsink attachment: Double-Side Tape, Epoxy or other mechanical installation.
EcoGreen Technologies offer offer various type of thermal pad, adhesive and other mechanical installation for different packages.

BGA HEATSINK



Thermal pad

PART NO	"W"	"A"	"H"	Type
2752A705	10.20	11.10	10.20	OD
1101A405	15.00	15.00	10.00	OD
1027A405	16.00	16.25	16.25	BD
1072A410/526	20.00	20.00	10.00	OD
1074A410/760	23.00	23.00	18.00	OD
1073A410/760	23.00	23.00	25.00	OD
1115A760	23.00	23.00	25.00	OD
2001A000	24.00	24.00	15.00	OD
1104A000	25.00	25.00	6.00	OD
1102A760	25.00	25.00	6.20	OD
1038A410	25.40	25.40	11.40	OD
2650A000	26.50	26.50	30.00	BD
2753A000	27.00	27.00	11.40	BD
1112A760	27.90	27.90	15.24	OD
1147A412	28.00	28.00	7.80	OD
1109A760	28.00	28.00	11.20	OD
1078A410/760	28.07	28.00	15.24	OD
1044A526	28.60	28.60	10.00	OD
1062A405	28.70	28.00	15.24	OD
1089A405	30.00	30.00	7.20	OD
1108A760	30.00	30.00	15.00	OD
2038A000	30.00	30.00	25.00	OD
2000A000	33.00	33.00	7.50	OD
1198A000	34.50	35.50	10.00	BD
2718A705	35.00	35.00	7.00	OD
1110A405	35.00	35.00	18.00	OD
1120A526	35.00	35.00	18.00	OD
1037A526	35.00	35.00	25.00	OD
1094A525	37.50	37.50	23.00	OD
1149A000	37.50	37.50	45.00	OD
1045A760	37.50	38.00	23.00	OD
1163A000	37.97	38.10	10.16	OD
1142A405	40.00	40.00	5.00	OD
1126A000	40.00	40.00	5.90	OD
1177A000	40.00	40.00	9.80	OD
1092A760	40.00	40.00	11.30	OD
1068A405	40.00	40.00	25.00	OD
1114A405	42.34	42.34	35.00	OD
1121A760	42.50	42.50	15.24	OD
1161A405	42.93	43.18	8.00	OD
1179A405	45.00	45.00	6.00	OD
1125A000	45.72	44.58	6.98	OD

* BD: Bidirection

OD: Omnidirection

Note: Heatsink attachment: Double-Side Tape or Epoxy. EcoGreen Technologies offer various type of thermal pad and adhesive for different packages & application.



BGA HEATSINK

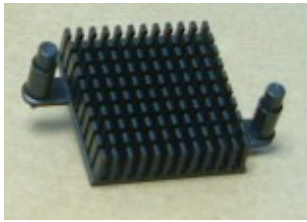


Fig.1

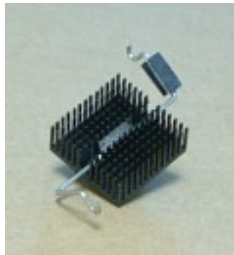
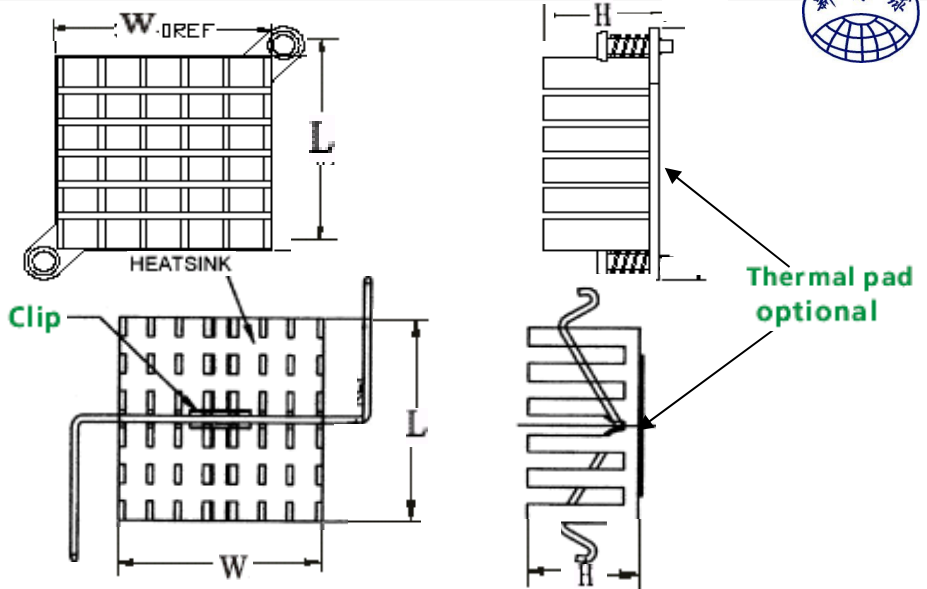


Fig. 2



PART NO	"W"	"L"	"H"	Fig.
1074A888	23.00	23.00	18.00	2
1073A888	23.00	23.00	25.00	2
1153A801	28.00	28.00	6.00	1
1120A888	35.00	35.00	18.00	2
1143A801	35.00	47.90	11.40	1
1139A801	35.50	35.50	10.00	1
1100A801	35.50	35.50	19.20	1
1098A801	35.50	35.60	10.00	1
1131A888	37.00	37.00	15.00	2
1158A889	37.20	38.00	10.00	2
1155A801	37.40	37.40	6.00	1
1156A801	37.40	37.40	10.00	1
1148A525	37.50	37.50	16.00	1
1094A888	37.50	37.50	23.00	2
1152A889	37.50	37.50	35.00	2
1149A889	37.50	37.50	45.00	2
1113A888	37.50	38.00	23.00	2
1090A801	37.60	37.50	20.00	1
1137A801	37.60	37.50	29.00	1
1091A801	37.60	37.60	22.80	1
1162A525	37.80	37.40	12.80	1
1164A801	37.80	37.56	29.00	1
1165A801	37.90	38.00	22.80	1
1135A801	38.00	38.00	11.90	1
1136A801	39.63	48.77	16.26	1
2014A888	40.00	40.00	25.00	2
1115A888	42.34	42.34	23.01	2
1114A888	42.34	42.34	35.00	2
1144A888	42.80	38.00	15.00	2
1145A889	42.80	38.00	22.30	2
1146A889	42.80	40.00	10.00	2
1138A801	45.00	48.00	33.00	1
1140A801	45.20	41.00	11.68	1
1128A801	45.30	41.40	11.50	1
1129A801	50.80	41.30	11.68	1

BGA ACTIVE HEATSINK

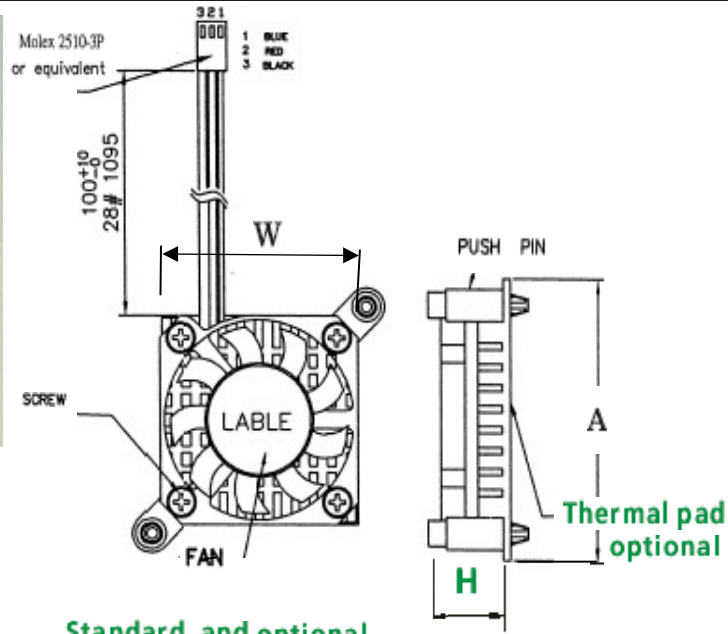


Fig.1

Standard and optional

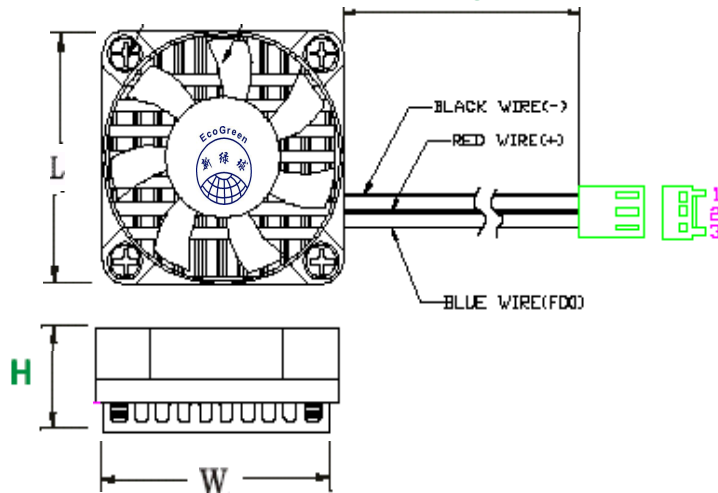


Fig.2

PART NO	"W"	"A"	"H"	Fig.	Fan
1122A	37.00	48.70	13.30	1	5V
2011A	37.40	37.40	11.50	2	5V
1176A	37.50	48.70	19.20	1	5V
2012A	37.50	48.72	19.20	1	12V
1053A	40.00	56.70	18.68	1	5V
1080A	40.00	56.70	21.05	1	5V
1081A	40.00	56.70	21.70	1	5V
1117A	40.00	56.70	14.90	1	12V
1159A	40.00	56.70	13.30	1	12V
1077A	40.00	40.00	21.50	2	12V
1180A	41.20	56.70	21.68	1	12V

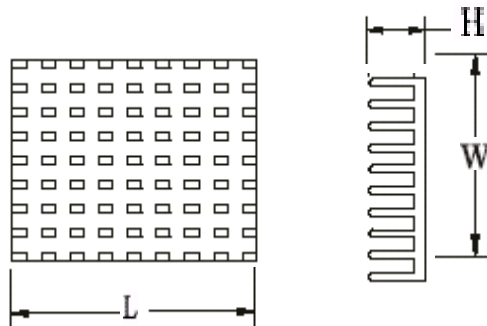
Note: The thermal pad is option material. Customer can order our standard thermal interface material. to enhance the thermal conductivity and performance.

BGA HEATSINK



<p>1257A000</p>			
<p>1258A000</p>			
<p>1259A000</p>			
<p>1260A000</p>			
<p>1261A000</p>			
<p>1262A000</p>			

BGA HEATSINK



PART NO	"W"	"L"	"H"	Type
1123A000	20.00	16.00	10.00	OD
1130A000	20.00	30.40	10.00	OD
1154A000	20.60	13.10	8.35	OD
1262A000	21.30	14.00	11.50	BD
1187A000	21.90	13.20	11.70	OD
1133A000	22.00	31.50	12.00	OD
1134A000	25.00	32.00	10.00	OD
1196A000	34.50	54.00	10.00	BD
1197A000	34.50	54.00	10.00	OD
1111A000	54.10	47.29	25.40	OD
2004A000	54.10	47.30	24.90	OD
1190A760	63.60	18.00	8.50	BD

* BD: Bidirection. OD: Omnidirection

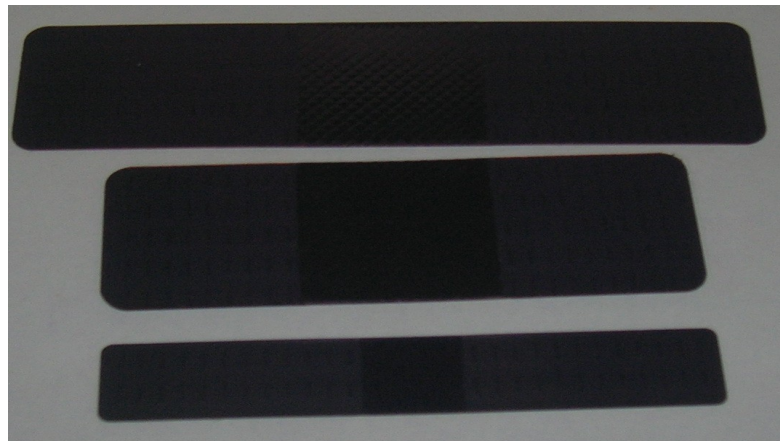
Installation of Heat Sink: Double-sided Thermal Tape, Mechanical Pins, Epoxy etc.

FLEXIBLE COPPER HEAT SPREADER

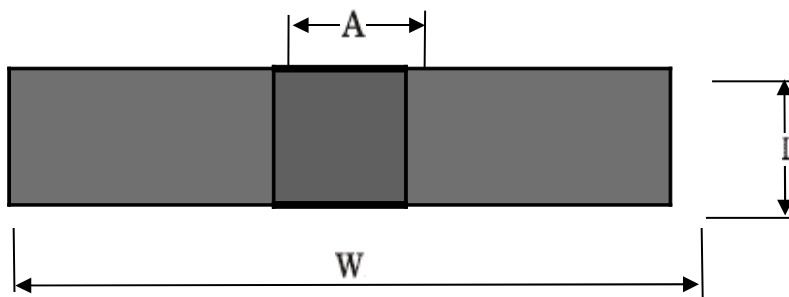
For PQFP, PGA, SQFP, CQFP, AGP and PCI Chip Set Application



FLEXIBLE COPPER HEAT SPREADER provide an effective method of cooling IC devices in Restricted space environment where conventional heat sinks can't be used.



FLEXIBLE COPPER HEAT SPREADER consists of Copper with electrically insulated film laminated on Both sides. Attachment is easy accomplished with a high bond strength, pressure sensitive adhesive for Excellent bonding to plastic, metal and ceramic surface.



PART NO	"W"	"L"	"A"
20264	50.80	12.70	12.70
20265	76.20	12.70	12.70
20366	76.20	19.10	19.10
20267	76.20	25.40	25.40
20268	101.60	25.40	25.40
20269	101.60	38.10	38.10